



## General Description

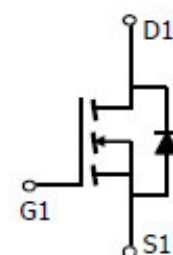
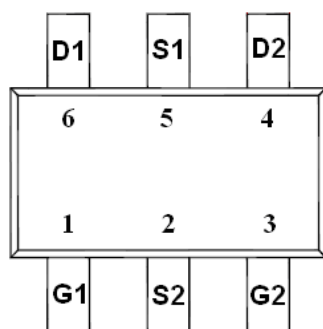
AFC6606W, N & P Pair enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

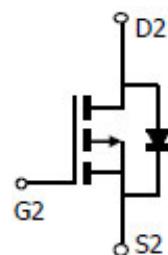
## Features

- N-Channel  
60V/2.8A,  $R_{DS(ON)}=135m\Omega@V_{GS}=10V$   
60V/2.0A,  $R_{DS(ON)}=145m\Omega@V_{GS}=4.5V$
- P-Channel  
-60V/-1.8A,  $R_{DS(ON)}=310m\Omega@V_{GS}=-10V$   
-60V/-1.4A,  $R_{DS(ON)}=340m\Omega@V_{GS}=-4.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23-6L package design

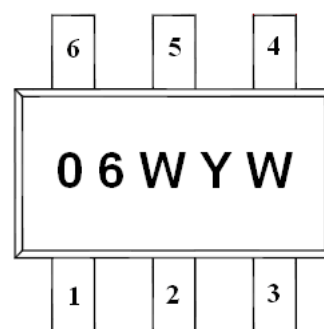
## Pin Description ( SOT-23-6L )



n-channel



p-channel



## Application

- LED Backlight
- DC/DC Converter
- Load Switch for Portable Applications

## Pin Define

Pin	Symbol	Description
1	G1	Gate 1
2	S2	Source 2
3	G2	Gate 2
4	D2	Drain 2
5	S1	Source 1
6	D1	Drain1

## Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFC6606WS26RG	06WYW	SOT-23-6L	Tape & Reel	3000 EA

※ 06W parts code

※ Y year code ( 0 ~ 9 )

※ W week code ( A ~ Z = 1 ~ 26 / a ~ z = 27 ~ 52 )

※ AFC6606WS26RG : 7" Tape & Reel ; Pb- Free ; Halogen- Free



**Absolute Maximum Ratings**

(T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Typical		Unit	
		N-Channel	P-Channel		
Drain-Source Voltage	V <sub>DSS</sub>	60	-60	V	
Gate –Source Voltage	V <sub>GSS</sub>	±20	±20	V	
Continuous Drain Current(T <sub>J</sub> =150°C)	I <sub>D</sub>	T <sub>A</sub> =25°C	-2.8	-1.8	A
		T <sub>A</sub> =70°C	-2.0	-1.4	
Pulsed Drain Current	I <sub>DM</sub>	-8	-8	A	
Continuous Source Current(Diode Conduction)	I <sub>S</sub>	-1.5	-1.5	A	
Power Dissipation	P <sub>D</sub>	T <sub>A</sub> =25°C	2.0	W	
		T <sub>A</sub> =70°C	1.3		
Operating Junction Temperature	T <sub>J</sub>	150		°C	
Storage Temperature Range	T <sub>STG</sub>	-55/150		°C	
Thermal Resistance-Junction to Ambient	R <sub>θJA</sub>	120		°C/W	

**Electrical Characteristics ( N-Channel )**

(T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	60			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	0.7		2.5	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =48V, V <sub>GS</sub> =0V			1	uA
		V <sub>DS</sub> =48V, V <sub>GS</sub> =0V T <sub>J</sub> =85°C			10	
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 5V, V <sub>GS</sub> =10V	5			A
Drain-Source On-Resistance	R <sub>Ds(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =2.8A		115	135	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =2.0A		125	145	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =2.0A		5		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =2.5A, V <sub>GS</sub> =0V		0.85	1.2	V
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =4.5V I <sub>D</sub> ≡2.0A		2.5	3.5	nC
Gate-Source Charge	Q <sub>gs</sub>			0.8		
Gate-Drain Charge	Q <sub>gd</sub>			1.0		
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V f=1MHz		200		pF
Output Capacitance	C <sub>oss</sub>			20		
Reverse Transfer Capacitance	C <sub>rss</sub>			10		
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V, R <sub>L</sub> =20Ω I <sub>D</sub> ≡1.5A, V <sub>GEN</sub> =10V R <sub>G</sub> =1Ω		4	8	ns
	t <sub>r</sub>			10	20	
Turn-Off Time	t <sub>d(off)</sub>			10	40	
	t <sub>f</sub>			6	10	



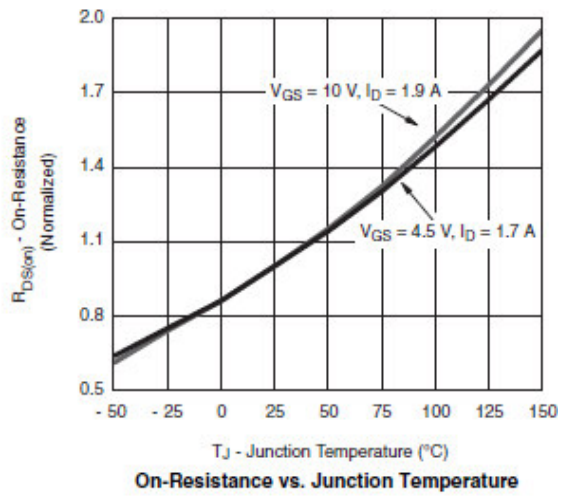
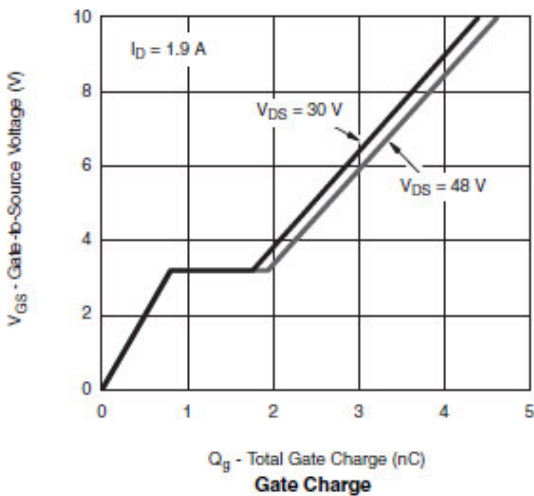
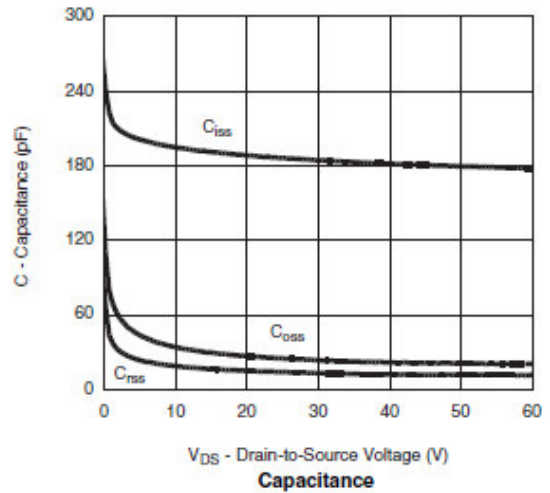
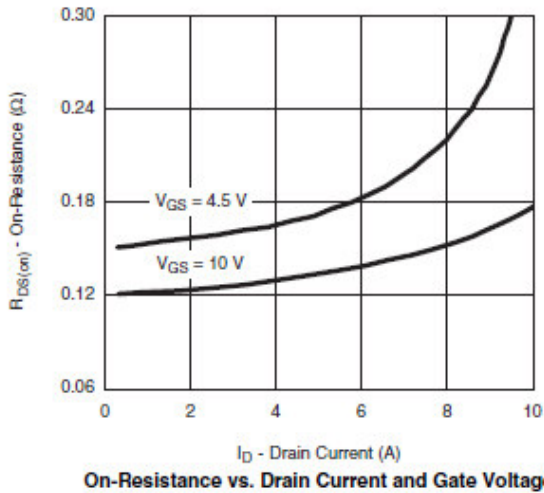
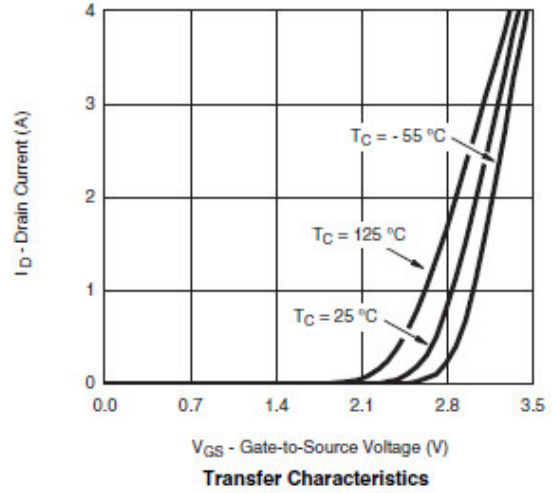
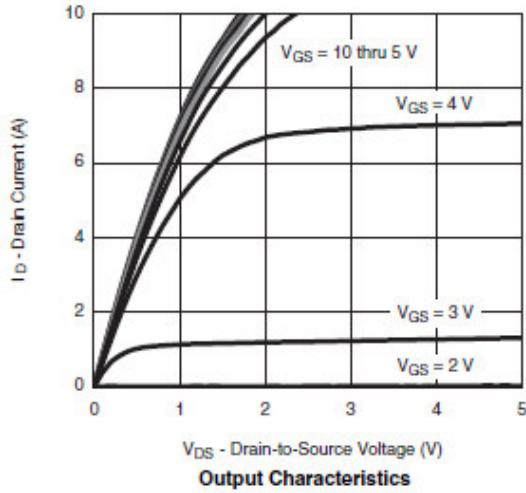
**Electrical Characteristics ( P-Channel )**

(T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-60			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	-1.0		-2.0	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V			-1	uA
		V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V T <sub>J</sub> =85°C			-30	
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> ≤ -5V, V <sub>GS</sub> =-10V	-6			A
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-1.8A		280	310	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-1.4A		295	340	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-10V, I <sub>D</sub> =-1.0A		2.8		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-1.0A, V <sub>GS</sub> =0V		-0.75	-1.3	V
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-30V, V <sub>GS</sub> =-4.5V I <sub>D</sub> ≡-1.25A		2.7	4.5	nC
Gate-Source Charge	Q <sub>gs</sub>			0.7		
Gate-Drain Charge	Q <sub>gd</sub>			1.2		
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V f=1MHz		210		pF
Output Capacitance	C <sub>oss</sub>			25		
Reverse Transfer Capacitance	C <sub>rss</sub>			18		
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-30V, R <sub>L</sub> =30Ω I <sub>D</sub> ≡-1.0A, V <sub>GEN</sub> =-10V R <sub>G</sub> =1.0Ω		5	10	ns
	t <sub>r</sub>			10	20	
Turn-Off Time	t <sub>d(off)</sub>			15	30	
	t <sub>f</sub>			10	20	

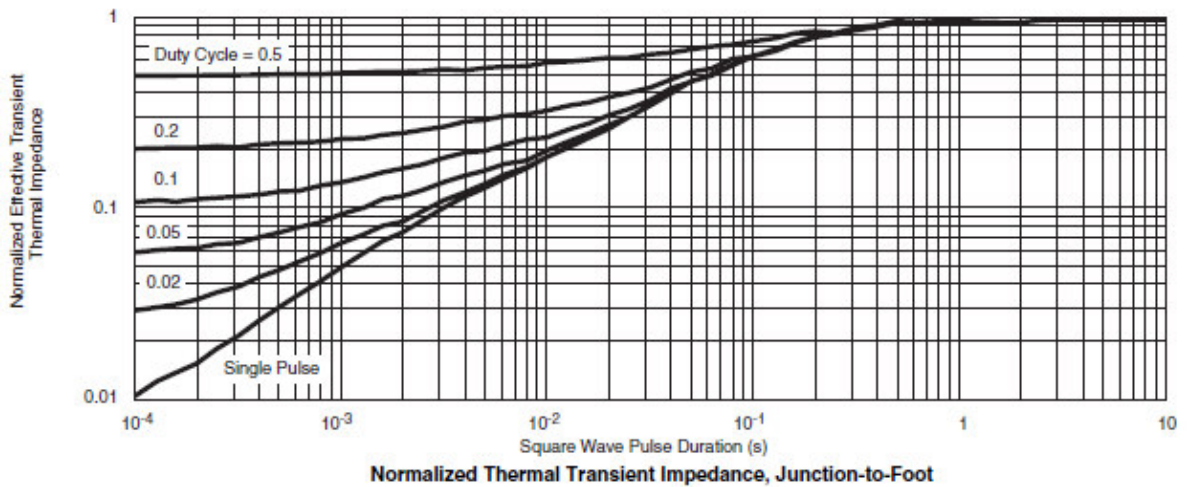
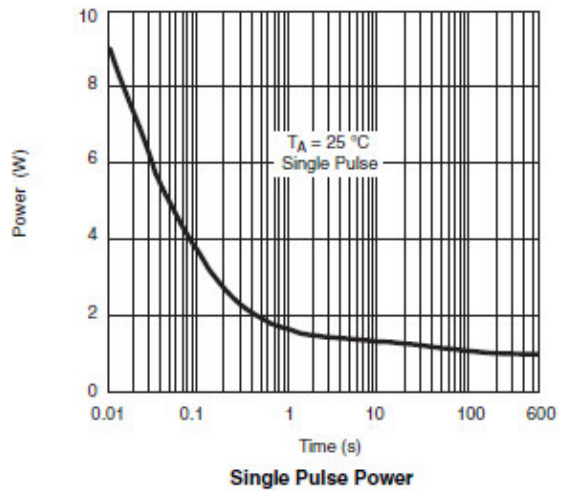
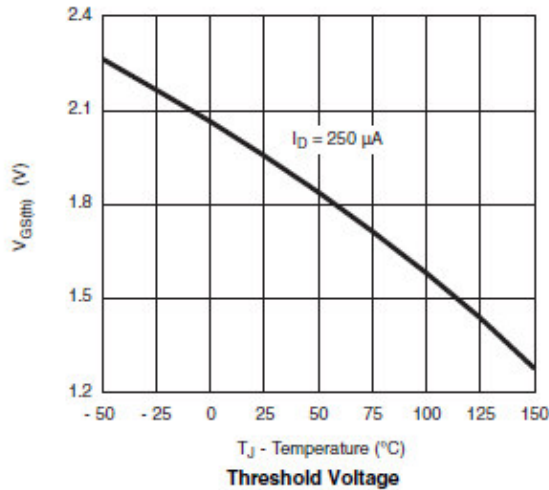
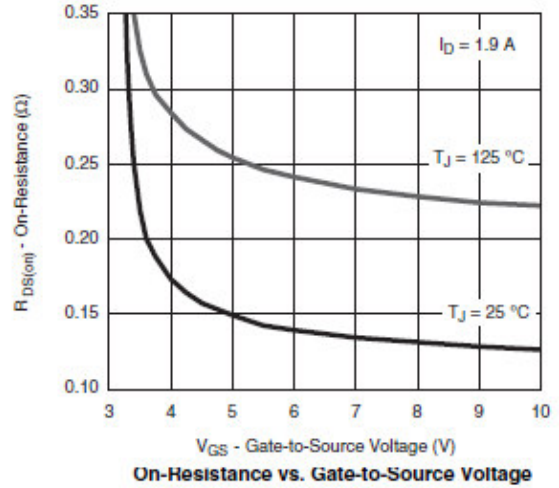
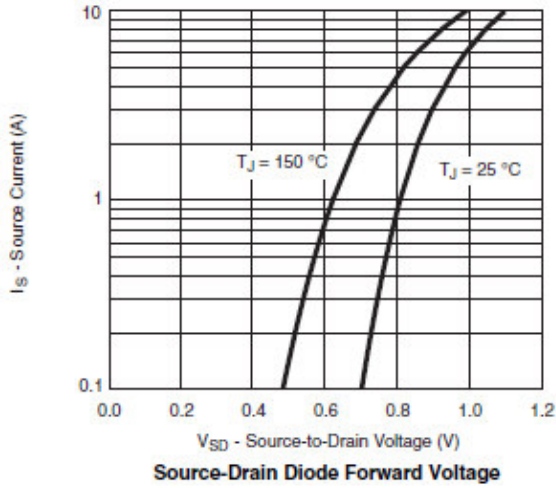


**Typical Characteristics ( N-Channel )**





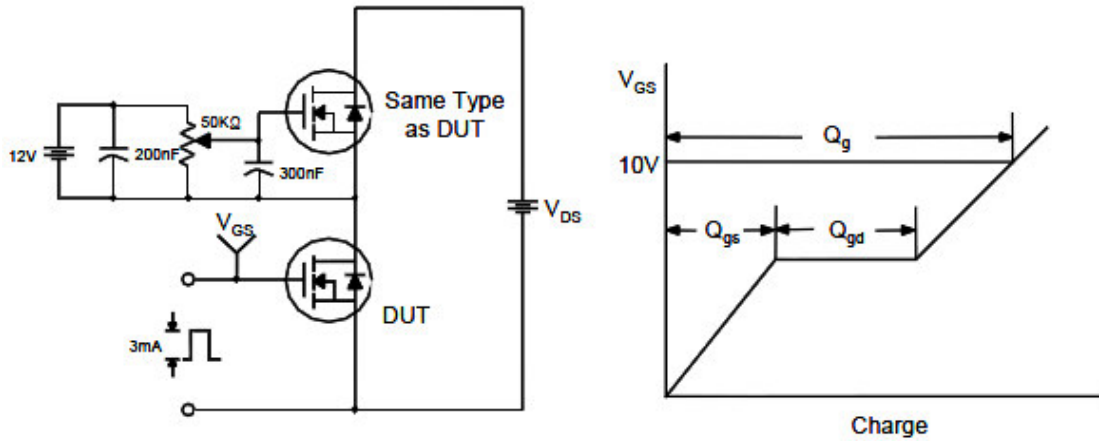
## Typical Characteristics ( N-Channel )



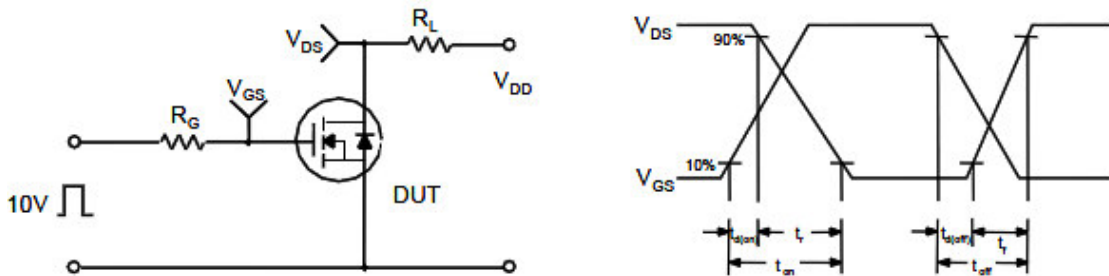


**Typical Characteristics ( N-Channel )**

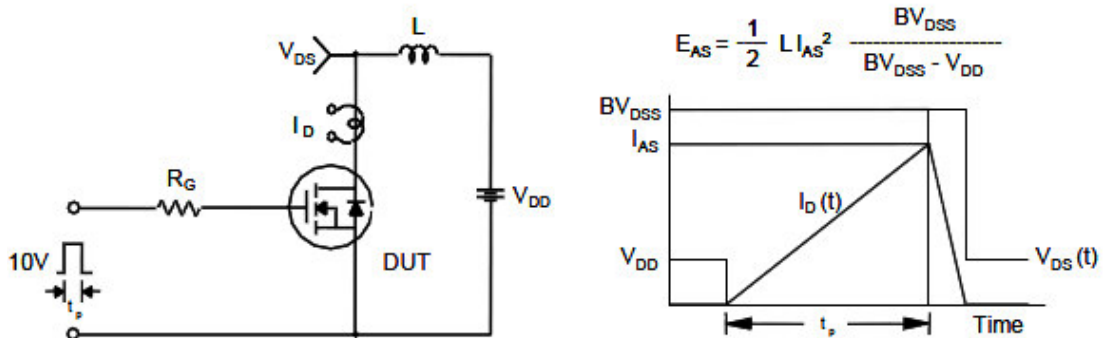
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

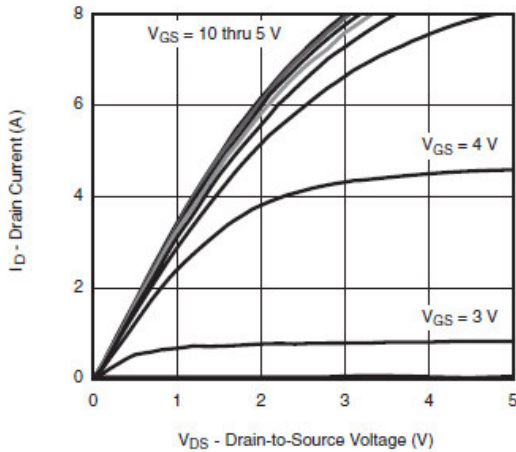


Unclamped Inductive Switching Test Circuit & Waveforms

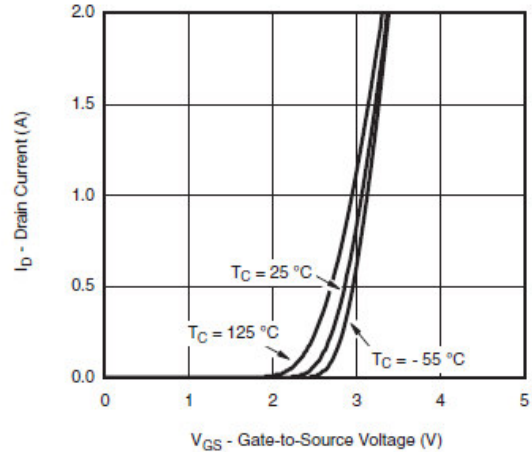




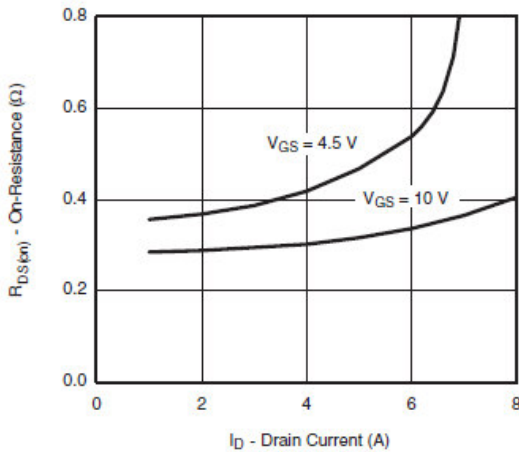
## Typical Characteristics ( P-Channel )



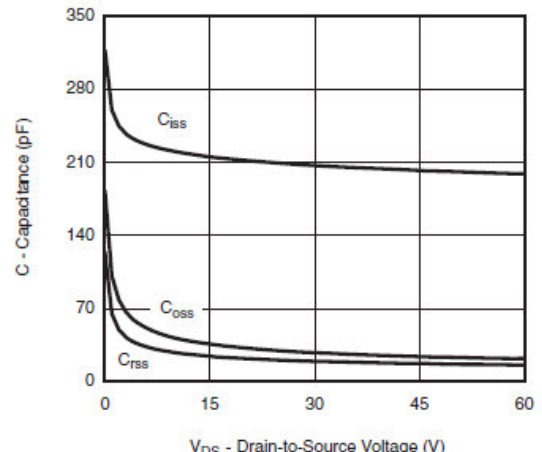
Output Characteristics



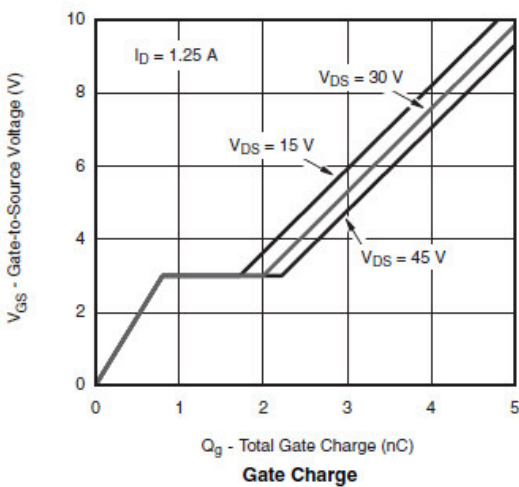
Transfer Characteristics



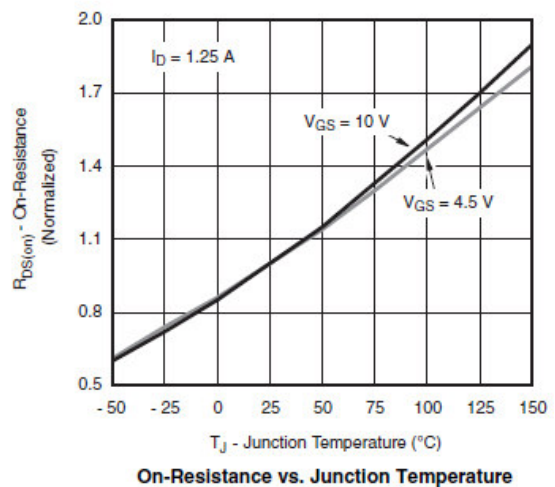
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



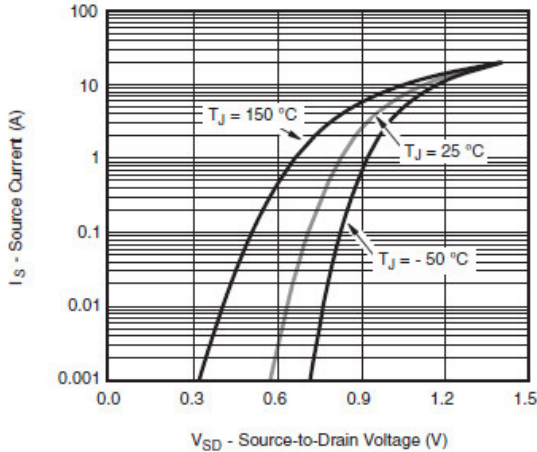
Gate Charge



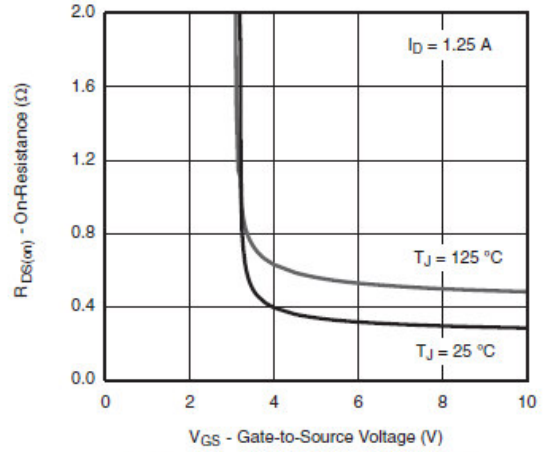
On-Resistance vs. Junction Temperature



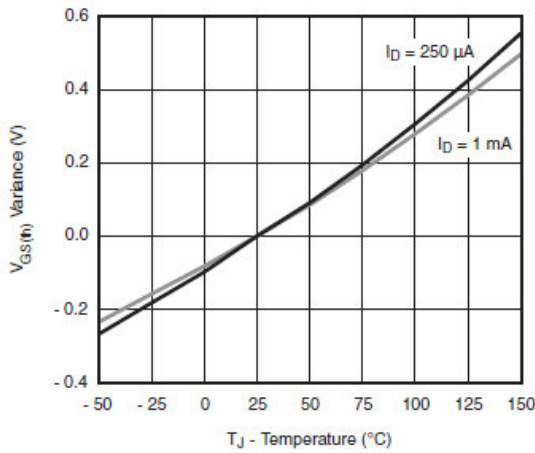
**Typical Characteristics ( P-Channel )**



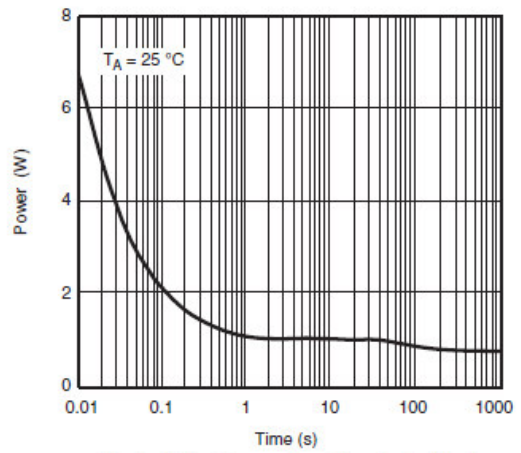
**Source-Drain Diode Forward Voltage**



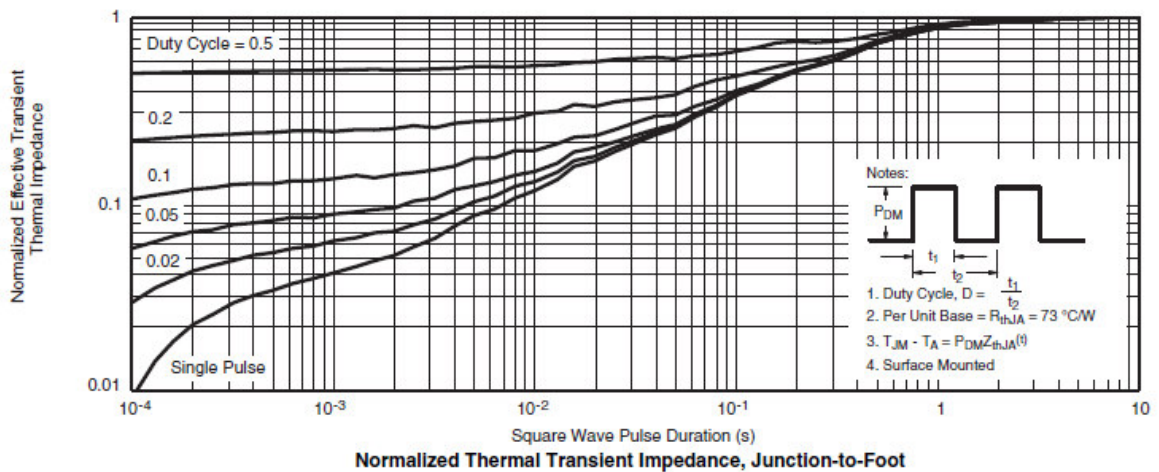
**On-Resistance vs. Gate-to-Source Voltage**



**Threshold Voltage**



**Single Pulse Power, Junction-to-Ambient**



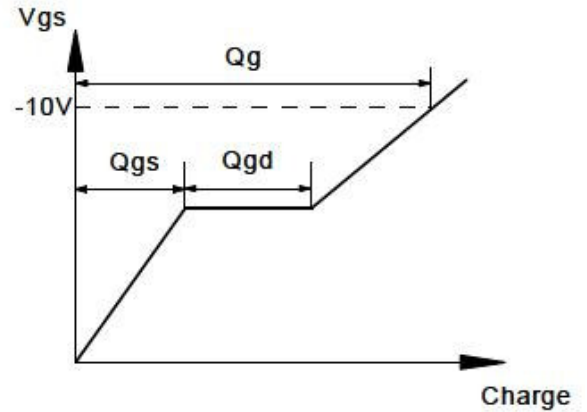
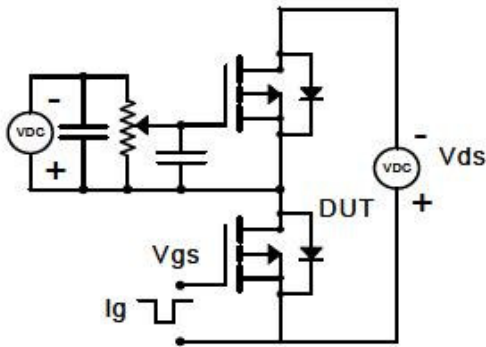
**Normalized Thermal Transient Impedance, Junction-to-Foot**



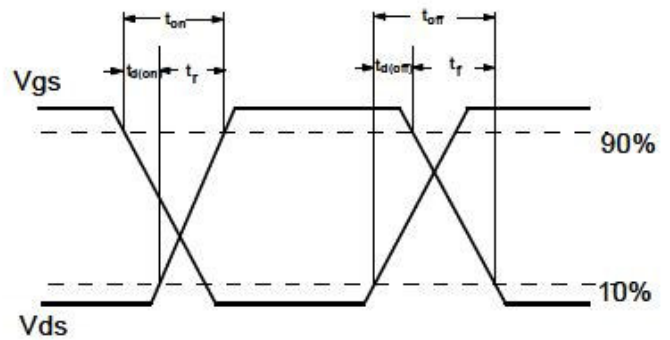
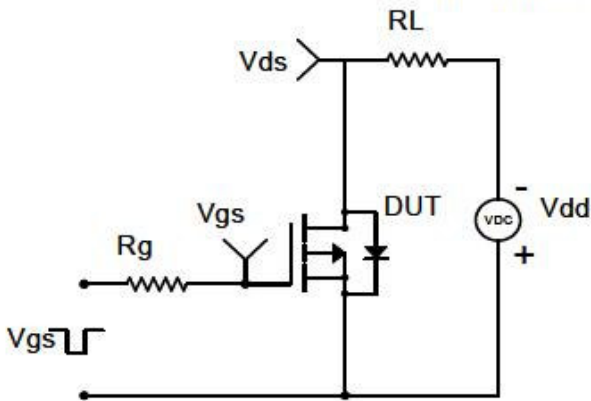


**Typical Characteristics**

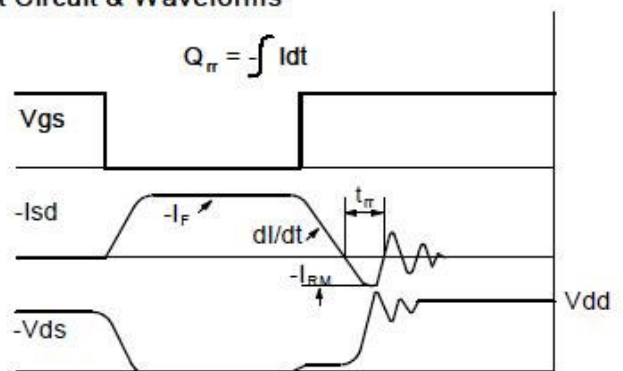
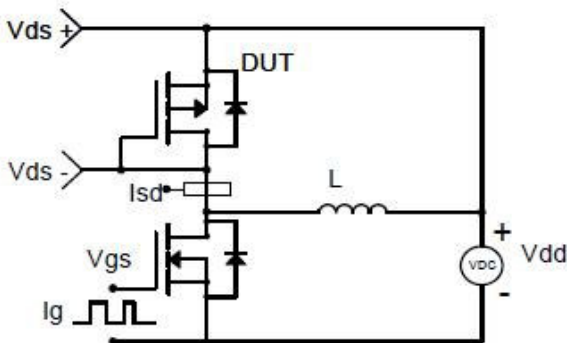
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

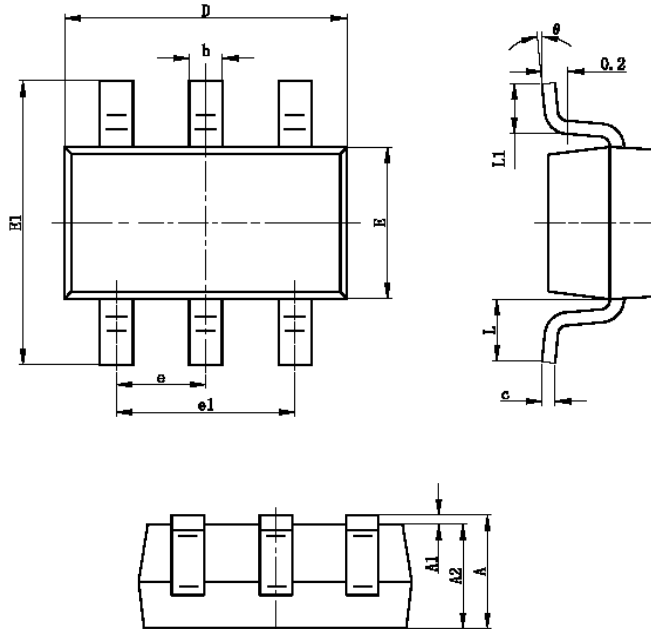


Diode Recovery Test Circuit & Waveforms





**Package Information ( SOT-23-6L )**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.400	0.012	0.016
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.700REF		0.028REF	
L1	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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